

AMENDMENT TO THE ABSTRACT

The following abstract will replace all prior versions of the abstract in the application:

ABSTRACT OF THE DISCLOSURE

A semiconductor device ~~(10)~~ includes an intermediate layer ~~(13)~~ provided between a semiconductor element and a heat sink ~~(12)~~. The intermediate layer moderates thermal stress resulting from a difference between thermal expansion of the semiconductor element and thermal expansion of the heat sink arising due to heat produced by the semiconductor element. This thermal stress moderation reduces warping of the semiconductor device as a whole.